

Applications

UPS, Welder, Inverter, Solar

Device	Package	Marking	Remark
TGH30N60F2DR	TO-247	TGH30N60F2DR	RoHS

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit	
Collector-Emitter Voltage	V_{CES}	600	V	
Gate-Emitter Voltage	V_{GES}	± 20	V	
Continuous Collector Current	I_C	$T_C = 25$	60	A
		$T_C = 100$	30	A
Pulsed Collector Current (Note 1)	I_{CM}	90	A	
Diode Continuous Forward Current	I_F	30	A	
Diode Pulsed Current (Note 2)	I_{FM}	90	A	
Power Dissipation	P_D	$T_C = 25$	278	W
		$T_C = 100$	139	W
Operating Junction Temperature	T_{vj}	-55 ~ 175		
Storage Temperature Range	T_{STG}	-55 ~ 150		
Maximum lead temperature for soldering purposes,	T_L	300		

Thermal Characteristics

Parameter	Symbol	Value	Unit
Maximum Thermal resistance, Junction-to-Case	R_{JC} (IGBT)	0.54	/W
Maximum Thermal resistance, Junction-to-Case	R_{JC} (DIODE)	1.43	/W
Maximum Thermal resistance, Junction-to-Ambient	R_{JA}	40	/W

Electrical Characteristics of the IGBT $T_{vj}=25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
OFF						
Collector Emitter Breakdown Voltage	BV_{CES}	$V_{GE} = 0V, I_C = 1mA$	600	--	--	V
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE} = 600V, V_{GE} = 0V$	--	--	1	mA
Gate Emitter Leakage Current	I_{GES}	$V_{CE} = 0V, V_{GE} = 20V$	--	--	250	nA
Integrated Gate Resistance	$R_{G(int)}$	$f = 1MHz, \text{Open Collector}$	--	3.7	--	
ON						
Gate Emitter Threshold Voltage	$V_{GE(TH)}$	$V_{GE} = V_{CE}, I_C = 30mA$	4.5	6.0	7.5	V
Collector Emitter Saturation Voltage	$V_{CE(SAT)}$	$V_{GE} = 15V, I_C = 30A, T_{vj} = 25$	--	1.45	1.95	V
		$V_{GE} = 15V, I_C = 30A, T_{vj} = 125$	--	1.59	--	V
		$V_{GE} = 15V, I_C = 30A, T_{vj} = 175$	--	1.70	--	V
DYNAMIC						
Input Capacitance	C_{IES}	$V_{CE} = 30V$ $V_{GE} = 0V$ $f = 1MHz$	--	2000	--	pF
Output Capacitance	C_{OES}		--	135	--	pF
Reverse Transfer Capacitance	C_{RES}		--	80	--	pF
Total Gate Charge	Q_g	$V_{CC} = 400V, I_C = 30A$ $V_{GE} = 15V$	--	135	202	nC
Gate-Emitter Charge	Q_{ge}		--	12	18	nC
Gate-Collector Charge	Q_{gc}		--	73	110	nC
SWITCHING (Note 3)						
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400V, I_C = 15A$ $R_G = 5 \Omega, V_{GE} = 15V$ Inductive Load, $T_{vj} = 25$	--	20	--	ns
Rise Time	t_r		--	14	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	98	--	ns
Fall Time	t_f		--	68	--	ns
Turn-On Switching Loss	E_{ON}		--	0.33	--	mJ
Turn-Off Switching Loss	E_{OFF}		--	0.26	--	mJ
Total Switching Loss	E_{TS}	--	0.59	--	mJ	
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400V, I_C = 30A$ $R_G = 5 \Omega, V_{GE} = 15V$ Inductive Load, $T_{vj} = 25$	--	23	--	ns
Rise Time	t_r		--	28	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	91	--	ns
Fall Time	t_f		--	38	--	ns
Turn-On Switching Loss	E_{ON}		--	0.74	1.11	mJ
Turn-Off Switching Loss	E_{OFF}		--	0.45	0.68	mJ
Total Switching Loss	E_{TS}	--	1.19	1.79	mJ	

Electrical Characteristics of the IGBT $T_{vj}=25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min.	Typ.	Max.	Unit
SWITCHING (Note 3)						
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400\text{V}, I_C = 15\text{A}$ $R_G = 5 \Omega, V_{GE} = 15\text{V}$ Inductive Load, $T_{vj} = 175$	--	21	--	ns
Rise Time	t_r		--	15	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	112	--	ns
Fall Time	t_f		--	156	--	ns
Turn-On Switching Loss	E_{ON}		--	0.65	--	mJ
Turn-Off Switching Loss	E_{OFF}		--	0.54	--	mJ
Total Switching Loss	E_{TS}		--	1.19	--	mJ
Turn-On Delay Time	$t_{d(on)}$	$V_{CC} = 400\text{V}, I_C = 30\text{A}$ $R_G = 5 \Omega, V_{GE} = 15\text{V}$ Inductive Load, $T_{vj} = 175$	--	24	--	ns
Rise Time	t_r		--	26	--	ns
Turn-Off Delay Time	$t_{d(off)}$		--	100	--	ns
Fall Time	t_f		--	135	--	ns
Turn-On Switching Loss	E_{ON}		--	1.27	1.91	mJ
Turn-Off Switching Loss	E_{OFF}		--	0.86	1.29	mJ
Total Switching Loss	E_{TS}		--	2.13	3.20	mJ
Short Circuit Withstanding Time	t_{SC}	$V_{CC} = 300\text{V}, V_{GE} = 15\text{V}, T_{vj} = 125^{\circ}\text{C}$	5	--	--	s

Notes :

(3) Not subject to production test verified by design/characterization

Electrical Characteristics of the DIODE $T_{vj}=25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	SymbolTest condition	Min.	Typ.	Max.	Unit
Diode Forward Voltage	V_{DF}	$I_{DF} = 10\text{A}$, $V_{CE} = 0\text{V}$				V
Diode Reverse Leakage Current	I_{R}	$V_{DR} = 600\text{V}$, $I_{DF} = 0\text{A}$				A
Diode Reverse Recovery Time	t_{rr}	$V_{DR} = 600\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				ns
Diode Reverse Recovery Charge	Q_{rr}	$V_{DR} = 600\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				nC
Diode Forward Recovery Time	t_{fr}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				ns
Diode Forward Recovery Charge	Q_{fr}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				nC
Diode Forward Recovery Time (Soft)	t_{frs}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				ns
Diode Forward Recovery Charge (Soft)	Q_{frs}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				nC
Diode Forward Recovery Time (Hard)	t_{frh}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				ns
Diode Forward Recovery Charge (Hard)	Q_{frh}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				nC
Diode Forward Recovery Time (Soft, High)	t_{frsh}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				ns
Diode Forward Recovery Charge (Soft, High)	Q_{frsh}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				nC
Diode Forward Recovery Time (Hard, High)	t_{frshh}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				ns
Diode Forward Recovery Charge (Hard, High)	Q_{frshh}	$V_{DF} = 10\text{V}$, $I_{DF} = 10\text{A}$, $I_{RR} = 10\text{A}$				nC

IGBT Characteristics

Fig. 1 IGBT Output Characteristics



Fig. 2 IGBT Output Characteristics

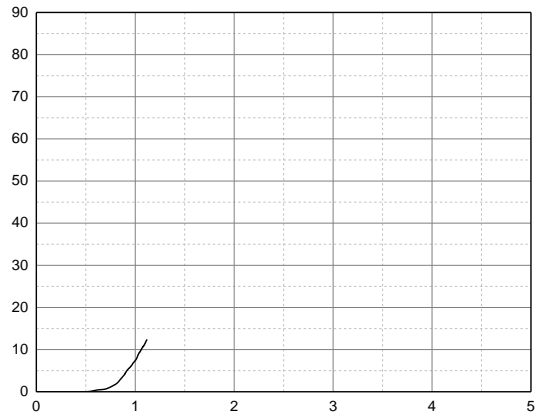


Fig. 3 IGBT Saturation Voltage vs. Junction Temperature

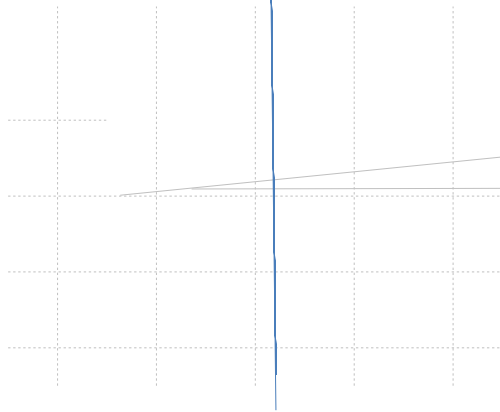


Fig. 4 IGBT Saturation Voltage vs. Gate Bias

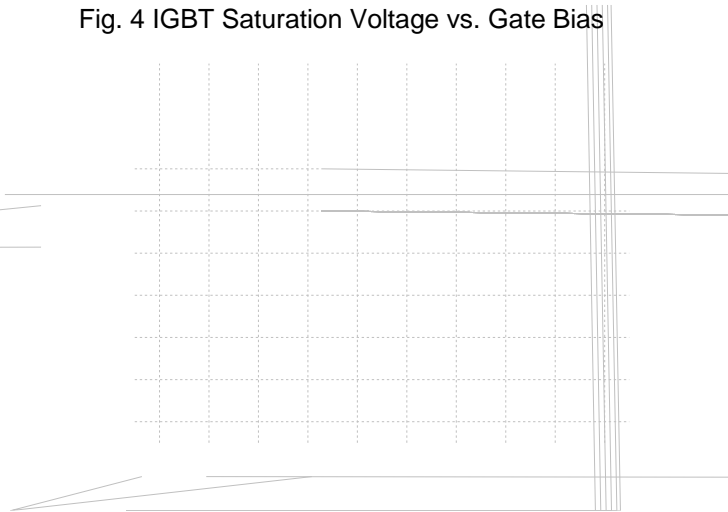
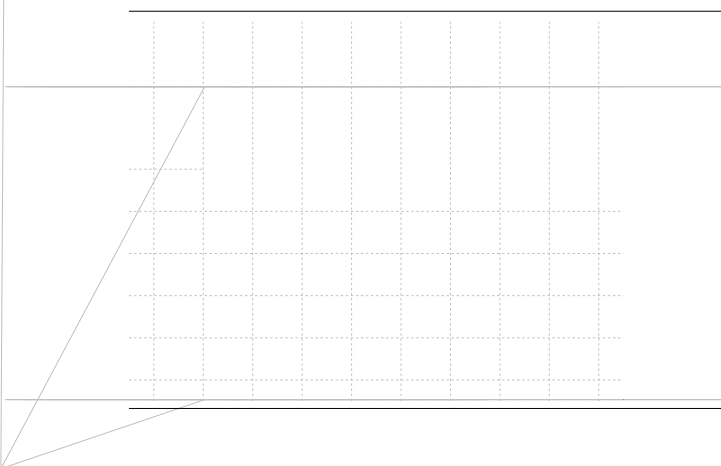
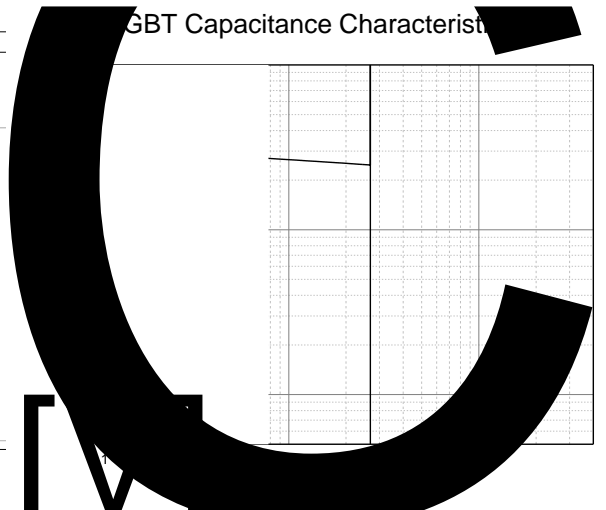


Fig. 5 IGBT Saturation Voltage vs. Gate Bias



IGBT Capacitance Characteristic



IGBT Characteristics

Fig. 7 Turn-on Time vs. Gate Resistor

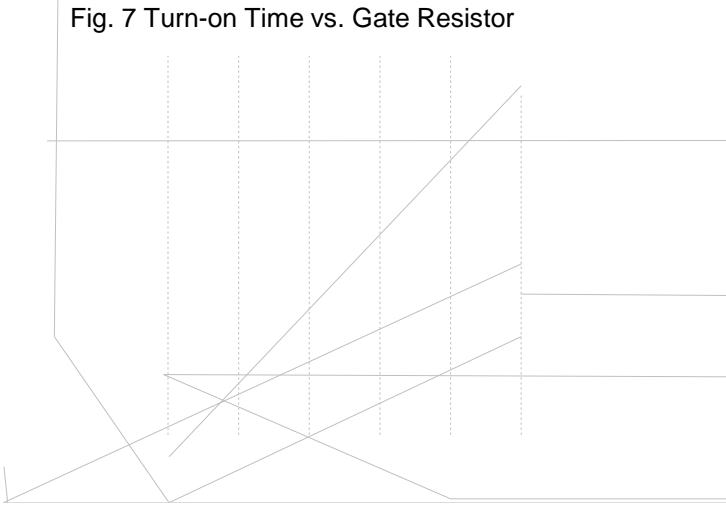


Fig. 8 Turn-off Time vs. Gate Resistor



Fig. 9 Switching Loss vs. Gate Resistor

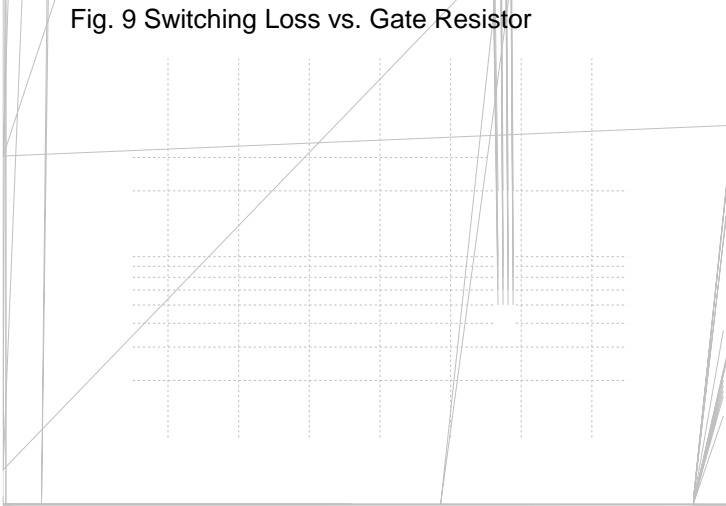


Fig. 10 Turn-on Time vs. Collector Current

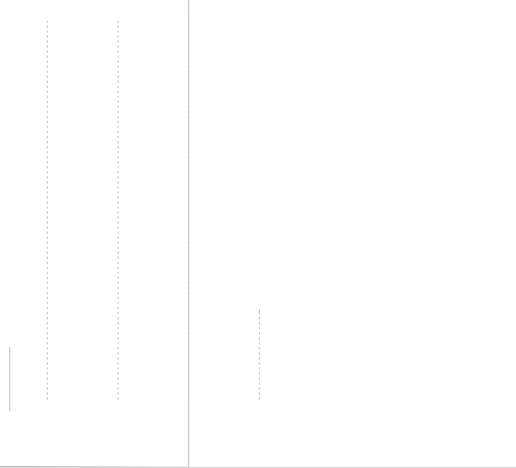


Fig. 11 Turn-off Time vs. Collector Current

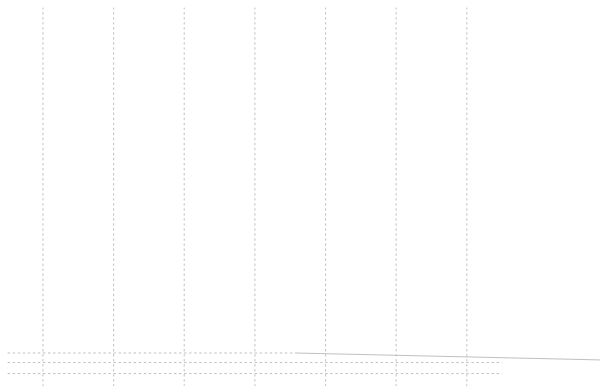
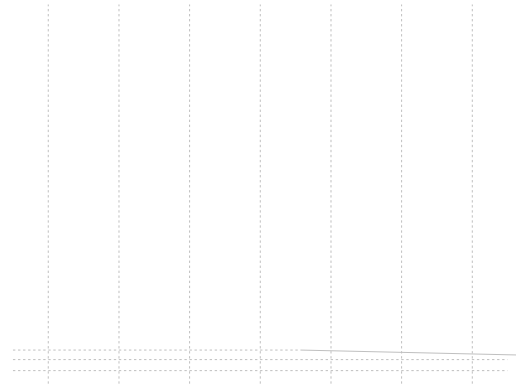


Fig. 12 Switching Loss vs. Collector Current



IGBT Characteristics

Fig. 13 Gate Charge Characteristics

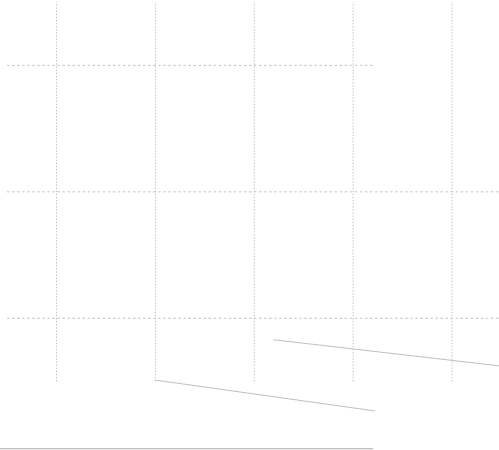


Fig. 14 SOA

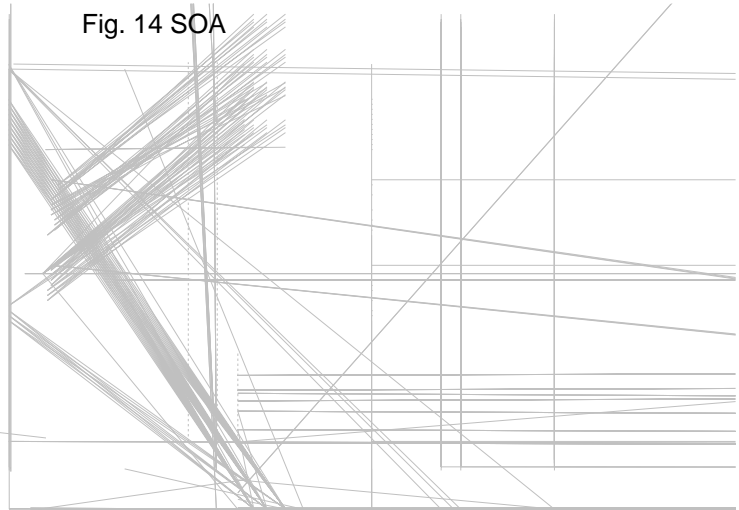


Fig. 15 RBSOA



Fig. 16 Transient Thermal Impedance of IGBT

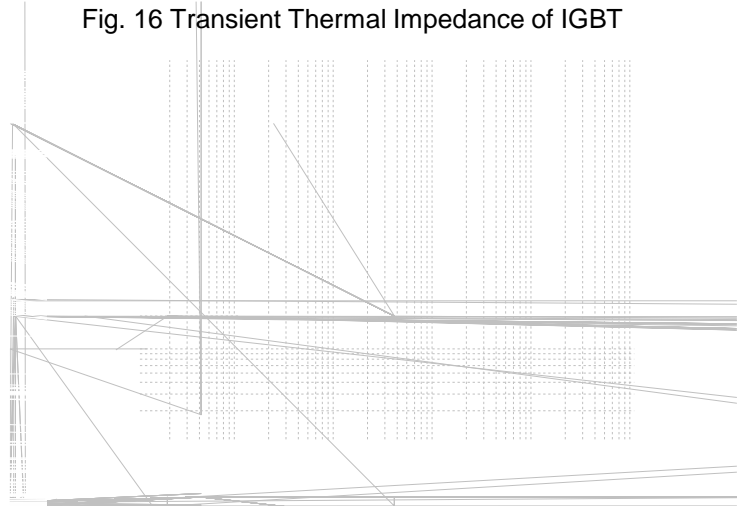
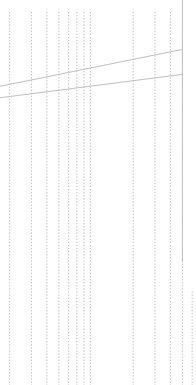


Fig. 17 Load Current vs. Frequency



Diode Characteristics

Fig. 18 Diode Conduction Characteristics

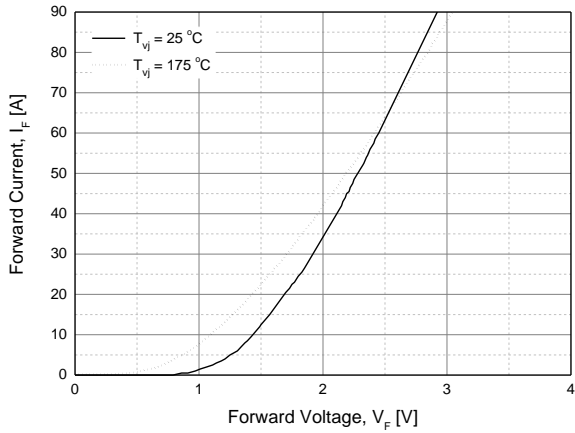


Fig. 19 Reverse Recovery Current vs. Forward Current

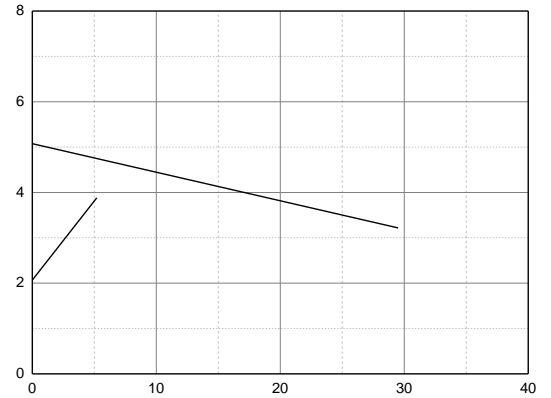


Fig. 20 Reverse Recovery Charge vs. Forward Current

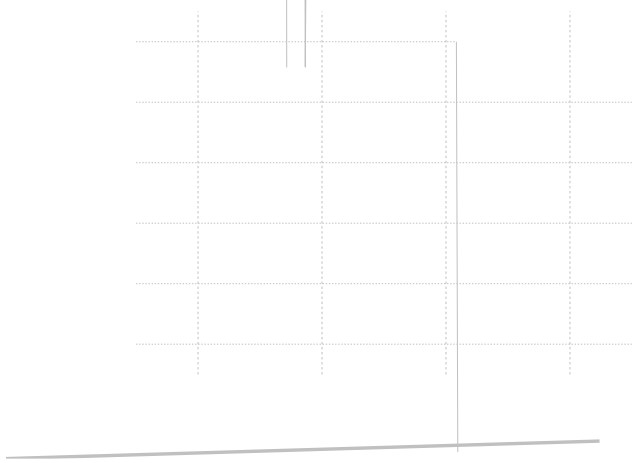
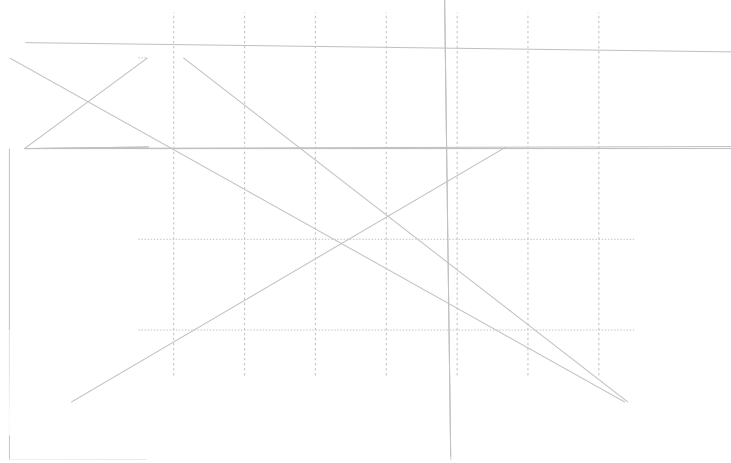
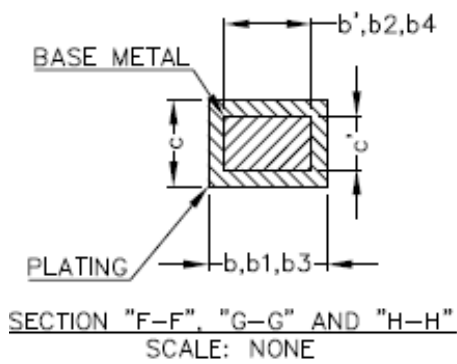
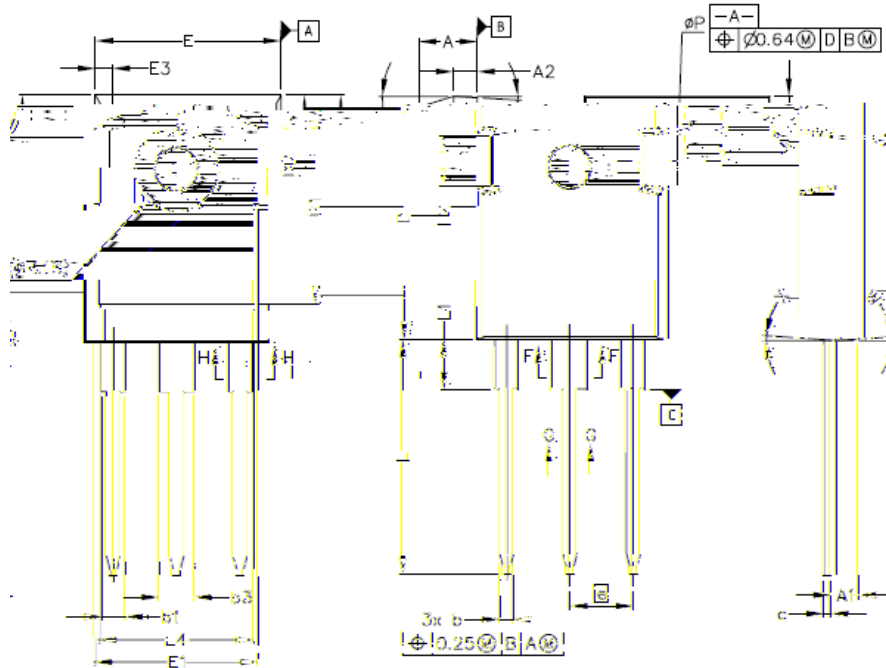


Fig. 21 Reverse Recovery Time vs. Forward Current



TO-247 MECHANICAL DATA



SYM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	.190	.205
A1	2.29	2.54	.090	.100
A2	1.91	2.16	.075	.085
b'	1.07	1.28	.042	.050
b	1.07	1.33	.042	.052
b1	1.91	2.41	.075	.095
b2	1.91	2.16	.075	.085
b3	2.87	3.38	.113	.133
b4	2.87	3.13	.113	.123
c'	0.55	0.65	.022	.026
c	0.55	0.68	.022	.027
D	20.80	21.10	.819	.831
D1	16.25	17.65	.640	.695
D2	0.95	1.25	.037	.049
E	15.75	16.13	.620	.635
E1	13.10	14.15	.516	.557
E2	3.68	5.10	.145	.201
E3	1.00	1.90	.039	.075
E4	12.38	13.43	.487	.529
e	5.44 BSC		.214 BSC	
N	3		3	
L	19.81	20.32	.780	.800
L1	4.10	4.40	.161	.173
φP	3.51	3.65	.138	.144
Q	5.49	6.00	.216	.236
S	6.04	6.30	.238	.248
T	17.5° REF.			
W	3.5° REF.			
X	4° REF.			

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